



TECHNICAL DATA SHEET

Sn99Ag1 SOLDER BAR

Lead Free



Description

Kurtel Sn99Ag1 alloy soldering bar can be used in lead-free applications and is manufactured in accordance with **RoHS II** (2011/65 / EU) directives. Sn99Ag1 alloy can be used as a feed ingot in order to reduce the copper ratio to desired values in tin-silver-copper ternary alloys. Increases the wetting performance with the Ag effect in its content.

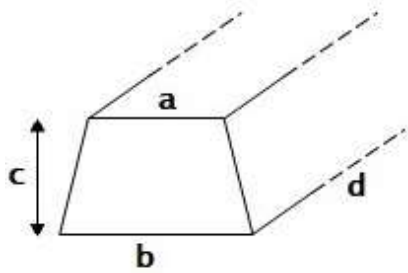
Advantages:

- RoHS II
- Fast wetting
- The effect of intermetallic compounds formed in its structure on mechanical properties
- Lower density than lead alloys

Physical Properties & Product Forms

Properties	Sn99Ag1
Solder composition:	Sn %99 ($\pm 0,15$) Ag %1 ($\pm 0,15$)
Melting Point:	221 °C Solidus 228 °C Liquidus
Specific Gravity:	7,33 g/cm ³

Kurtel Sn99Ag1 solder bar is trapezoidal 0,95 kg ingot form in 20kg box packages.



Dimensions

a : 20 mm
b : 24 mm
c : 17 mm
d : 350 mm





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Storage & Shelf Life

Dry at room temperature. Solder has an indefinite shelf life.

Health & Safety

Before using please read the MSDS

